



**PRINTED CIRCUIT BOARDS**  
**INTERCONNECTION CARRIERS**

State of the Art: PCB's

Revisio

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Seite:

**PRINTED CIRCUIT BOARDS**

**01**

**4.11.2001**

**1/1**


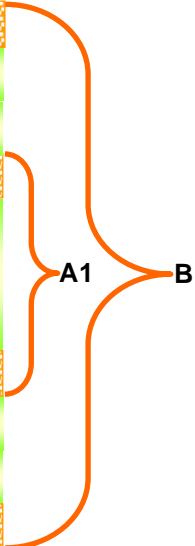


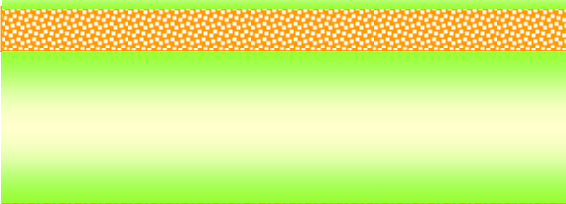




**Schematic Key for Multilayer and HDI-Technology Build-Ups**

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

**04 164 FR4 70 L71.35 P18**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_164\_FR4\_70\_L71.35\_p18**

| Layers          | in $\mu$  | Material | Build-Up   | Assembly   |
|-----------------|-----------|----------|--|--|
| <b>Layer-1</b>  | 70 $\mu$  | Copper   |    |  |
|                 | 180 $\mu$ | Prepreg  |  |  |
|                 | 180 $\mu$ | Prepreg  |    |  |
| <b>Layer-2</b>  | 35 $\mu$  | Copper   |    |  |
|                 | 710 $\mu$ | L-FR4    |   |  |
| <b>Layer-3</b>  | 35 $\mu$  | Copper   |  |  |
|                 | 180 $\mu$ | Prepreg  |  |  |
|                 | 180 $\mu$ | Prepreg  |  |  |
| <b>Layer-99</b> | 70 $\mu$  | Copper   |  |  |

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